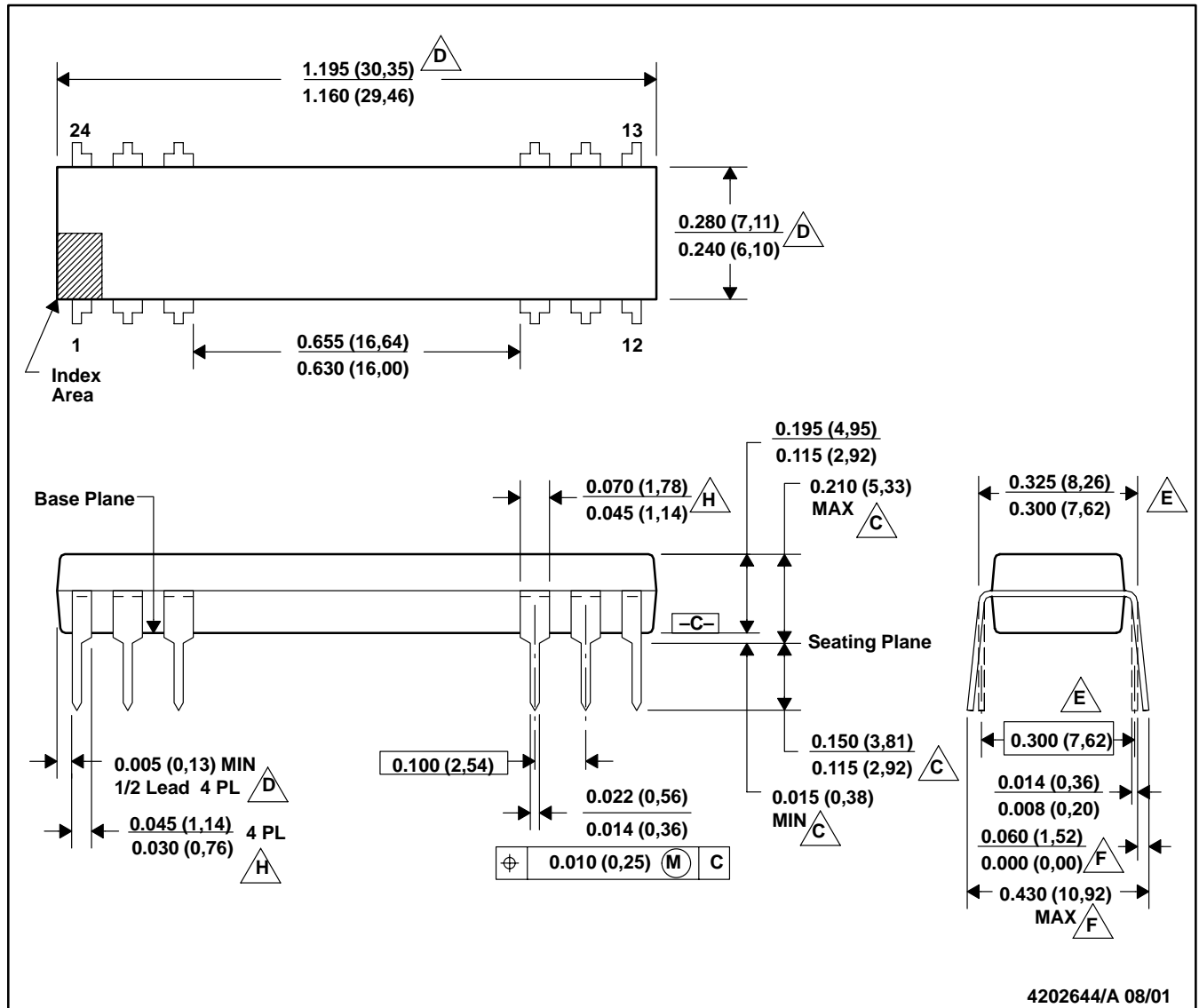


## NVG (R-PDIP-T12/24)

## PLASTIC DUAL-IN-LINE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Dimensions are measured with the package seated in JEDEC seating plane gauge GS-3.
  - Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 (0,25).
  - Dimensions measured with the leads constrained to be perpendicular to Datum C.
  - Dimensions are measured at the lead tips with the leads unconstrained.
  - Pointed or rounded lead tips are preferred to ease insertion.
  - Maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 (0,25).
  - Distance between leads including dambar protrusions to be 0.005 (0,13) minimum.
  - A visual index feature must be located within the cross-hatched area.
  - For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.
  - Controlling dimension in inches.
  - Falls within JEDEC-MS-001-BE with exception of lead count.

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